Application Number:	100	10666399					
Filing Date:	18-	18-Sep-2003					
Title of invention:	WC	MOLDED CHIP FABRICATION METHOD					
First Named Inventor/Applicant Name:	Mid	Michael S. Leung					
Filer:	Jay	Jaye G. Heybl/Joan Harriman					
Attorney Docket Number:	PO	P0298US-7					
Filed as Large Entity							
Utility under 35 USC 111(a) Filing Fee	s						
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							

Publ. Fee- early, voluntary, or normal

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
	Total in USD (\$)			1810